

2.5/3.3V 200MHz High-Speed, Low-Jitter, Low-Skew, Zero-Delay Clock Buffer with 9 Outputs

Features

- Phase-Lock Loop Clock Distribution (Zero Input-to-Output Delay)
- Internal feedback connection
- Distributes one-to-two banks of four outputs w/ one CLKOUT (9 - outputs total)
- High-Performance
 - 30 MHz to 220 MHz operation frequency range
 - <100ps output-to-output skew
 - <100ps cycle-to-cycle jitter
 - Low Power Configuration - 26mA (outputs unloaded)
- Spread-spectrum capable
- Power supply: +2.5V $\pm 5\%$; +3.3V $\pm 10\%$
- Industrial temperature range parts available
- Packaging (Pb-free & Green):
 - 16-pin TSSOP (L)
 - 16-pin SOIC (W)

Description

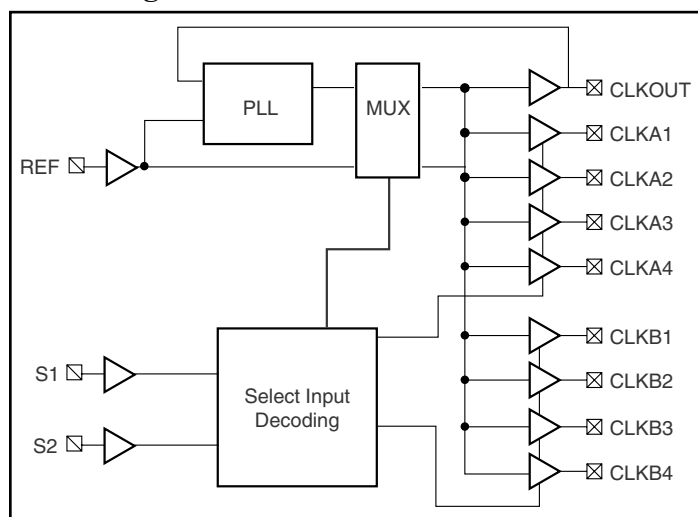
The PI6C22409 is a low-jitter, low-skew, high-speed Zero-Delay Buffer with 9 outputs designed to address high-speed clock distribution applications.

The PI6C22409 features an internal patented Phase Lock Loop (PLL) with high drive output capability and internal feedback.

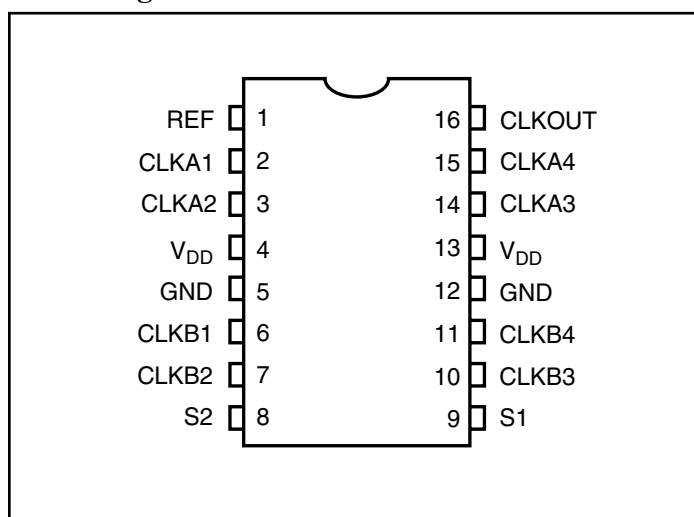
The PI6C22409 operates from a 2.5V $\pm 5\%$ or 3.3V $\pm 10\%$ supply. All support documentation can be found on Pericom's web site at: www.pericom.com.

Pericom can customize these devices for specific requirements.

Block Diagram



Pin Configuration



Pin Description

| Pin | Signal | Description |
|-------------------------|---|--|
| 1 | REF | Reference clock input with weak pull down. |
| 2,3,6,7, 10,11,14,15 | CLKA1, CLKA2, CLKB1, CLKB2, CLKB3, CLKB4, CLKA3, CLKA4, CLKOUT | Clock output. Clock outputs with weak pull-down. |
| 16 | CLKOUT | Clock output. Internal feedback on this pin. |
| 5,12 | GND | Ground |
| 4,13 | V _{DD} | Power |
| 8,9 | S2, S1 | Select input with weak pull-ups. |

Select Input Decoding

| S2 | S1 | Clock A1 - A4 | Clock B1 - B4 | CLKOUT | Output Source | PLL shutdown |
|----|----|---------------|---------------|--------|---------------|--------------|
| 0 | 0 | Tri-State | Tri-State | Driven | PLL | N |
| 0 | 1 | Driven | Tri-State | Driven | PLL | N |
| 1 | 0 | Driven | Driven | Driven | Reference | Y |
| 1 | 1 | Driven | Driven | Driven | PLL | N |

Maximum Ratings⁽¹⁾

| | |
|---|-----------------|
| Supply Voltage | |
| V _{DD} | -0.5V to +4.6V |
| REF | -0.5V to +4.6V |
| Input Current | -50mA |
| Output Current | ±50mA |
| Lead Temperature (cap soldering, 10 sec.) | +260°C |
| Storage Temperature (T _s) | -65°C to +150°C |
| Junction Temperature | +150°C |
| Operating Temperature (cap industrial) | -40°C to +85°C |
| Operating Temperature (cap commercial) | 0°C to +70°C |

Operation Ratings⁽²⁾

| | |
|---|--------------------|
| Supply voltage | |
| V _{DD} | +3.0V to +3.6V |
| V _{DD} | +2.375V to +2.625V |
| Ambient Temperature (T _A) | 0°C to +70°C |
| Package Thermal Resistance ⁽²⁾ | |
| θ _{JA} | |
| Still-Air (SOIC-16) | 89°C/W |
| Still-Air (SOIC-16) | 90°C/W |
| θ _{JB} | |
| Junction-to-Board (SOIC-16) | 26°C |
| Junction-to-Board (TSSOP-16) | 24°C |

Notes:

1. Stresses greater than those listed under Maximum Ratings may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of the this specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
2. θ_{JA} and θ_{JB} values are determined for a 4-layer board in still-air, unless otherwise stated.

DC Electrical Characteristics

| Parameter | Description | Test Conditions | Min. | Max. | Units |
|-----------------|---------------------|---|------------------------|------|-------|
| V _{IL} | Input LOW Voltage | V _{DD} = 3.3V | | 0.8 | V |
| | | V _{DD} = 2.5V | | 0.7 | |
| V _{IH} | Input HIGH Voltage | V _{DD} = 3.3V | 2.0 | | |
| | | V _{DD} = 2.5V | 1.7 | | |
| I _{IL} | Input LOW Current | V _{IN} = 0V | | 50 | μA |
| I _{IH} | Input HIGH Current | V _{IN} = V _{DD} | | 125 | |
| V _{OL} | Output LOW Voltage | I _{OL} = 12mA | V _{DD} = 3.3V | 0.4 | V |
| | | | V _{DD} = 2.5V | 0.5 | |
| V _{OH} | Output HIGH Voltage | V _{DD} = 2.5V, I _{OH} = -12mA | 1.8 | | |
| | | V _{DD} = 3.3V, I _{OH} = -12mA | 2.4 | | |
| I _{DD} | Supply Current | Unloaded outputs 66 MHz | | 32 | mA |

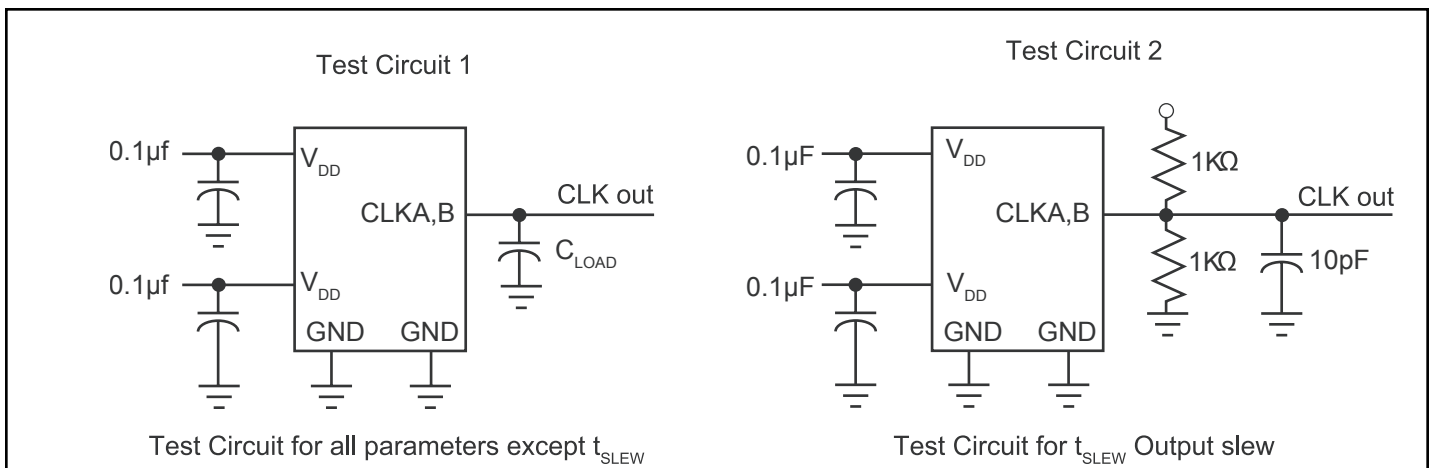
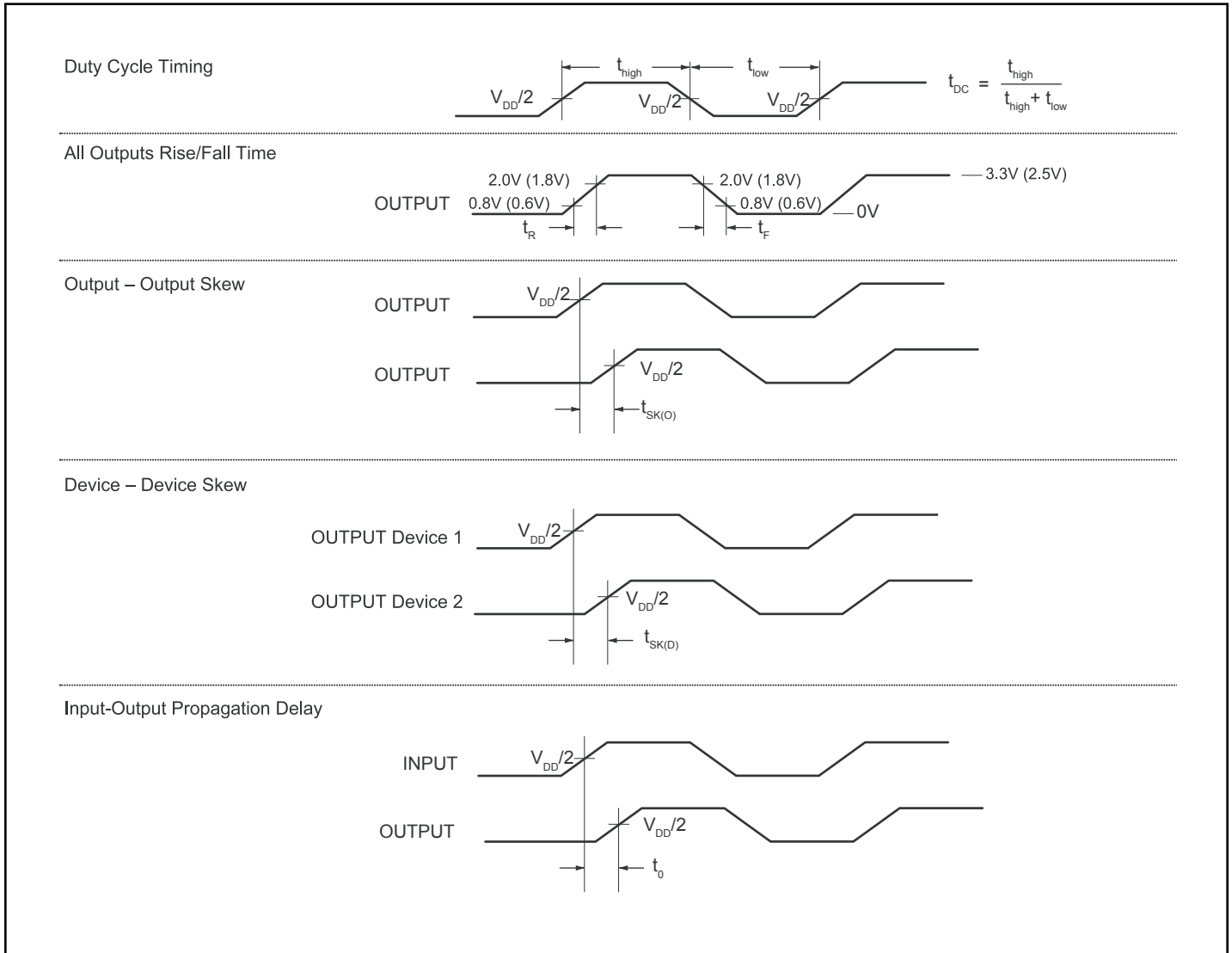
AC Electrical Characteristics

| Parameter | Description | Test Conditions | Min. | Typ. | Max. | Units | |
|----------------------------------|---|---|------------------------|------|------|-------|----|
| F _O | Output Frequency | V _{DD} = 2.5V | 10 | | 200 | MHz | |
| | | V _{DD} = 3.3V | 10 | | 220 | MHz | |
| BW | Bandwidth for PLL | V _{DD} = 2.5V | | 0.8 | | MHz | |
| | | V _{DD} = 3.3V | | 1.5 | | | |
| t _{DC} | Duty Cycle ⁽⁴⁾ | Measured at V _{DD} /2, 10 pF load | 45 | 50 | 55 | % | |
| t _R | Rise Time ⁽¹⁾⁽⁴⁾ | For 3.3V: Measured between 0.8V and 2.0V; @10pF | | | 1 | ns | |
| | | For 2.5V: Measured between 0.6V and 1.8V; @10pF | | | 1.8 | | |
| t _F | Fall Time ⁽¹⁾⁽⁴⁾ | For 3.3V: Measured between 0.8V and 2.0V; @10pF | | | 1 | ns | |
| | | For 2.5V: Measured between 0.6V and 1.8V; @10pF | | | 1.8 | | |
| t _{sk(o)} | Output to Output skew ⁽¹⁾ | All Outputs Equally Loaded | V _{DD} = 3.3V | | | 100 | ps |
| | | | V _{DD} = 2.5V | | | 100 | |
| t ₀ | Delay, REF Rising Edge to CLKOUT Rising Edge ⁽¹⁾ (2)(5) | Measured at V _{DD} /2, 66MHz | V _{DD} = 3.3V | -100 | | 100 | ps |
| | | | V _{DD} = 2.5V | -200 | 0 | 200 | |
| t _{SK(D)} | Device-to-device skew ⁽¹⁾ (3) | Measured at V _{DD} /2 on CLKx pins of device | -300 | 0 | +300 | ps | |
| t _{JIT} | Cycle-to-Cycle Jitter | 15pF load, >66MHz, standard drive | V _{DD} = 3.3V | | 47 | 110 | ps |
| | | | V _{DD} = 2.5V | | 42 | 90 | |
| | | 15pF load, >66MHz, high drive | V _{DD} = 3.3V | | 45 | 100 | |
| | | | V _{DD} = 2.5V | | 40 | 80 | |
| | | 30pF load, >66MHz, standard drive | V _{DD} = 3.3V | | 63 | 120 | |
| | | | V _{DD} = 2.5V | | 83 | 130 | |
| t _{PJ} | Period Jitter (Peak) | 15pF load, >66MHz, standard drive | V _{DD} = 3.3V | | 39 | 90 | ps |
| | | | V _{DD} = 2.5V | | 28 | 60 | |
| | | 15pF load, >66MHz, high drive | V _{DD} = 3.3V | | 39 | 85 | |
| | | | V _{DD} = 2.5V | | 27 | 55 | |
| | | 30pF load, >66MHz, standard drive | V _{DD} = 3.3V | | 48 | 85 | |
| | | | V _{DD} = 2.5V | | 75 | 90 | |
| 30pF load, >66MHz, high drive | V _{DD} = 3.3V | | 43 | 75 | | | |
| | V _{DD} = 2.5V | | 60 | 80 | | | |
| t _{LOCK} | PLL Lock time ⁽¹⁾ | Stable power supply, valid clocks presented on CLKOUT pin | | | 1 | ms | |

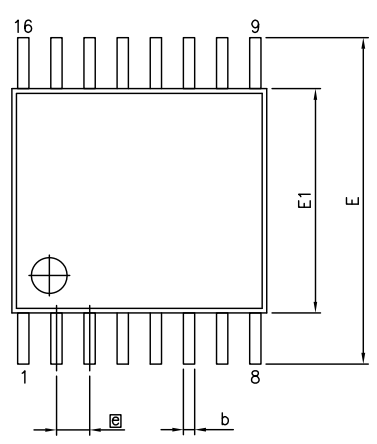
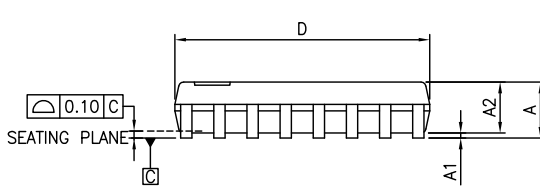
Note:

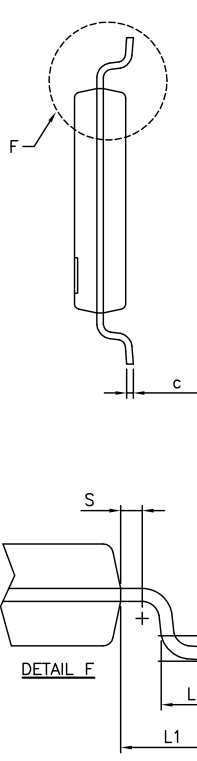
- See Switching Waveforms
- All clock output should have the same loading to achieve zero delay between the input and outputs and zero output-to-output skew. Since the CLKOUT pin is the internal feedback to the PLL, its relative loading can adjust to input-to-output delay. If input-to-output delay adjustments are needed, the CLKOUT load may be changed to vary the delay between the REF input to the clock outputs. Output-to-output skew includes CLKA1-4 and CLKB1-4.
- Specifications are guaranteed by design and not production tested.
- Measured at 100MHz.
- Measured with 16-Pin SOIC package

Switching Waveforms



Packaging Mechanical: 16-Pin TSSOP (L)







| VARIATIONS (ALL DIMENSIONS SHOWN IN MM) | | | |
|---|----------|------|------|
| SYMBOLS | MIN. | NOM. | MAX. |
| A | — | — | 1.20 |
| A1 | 0.05 | — | 0.15 |
| A2 | 0.80 | — | 1.05 |
| b | 0.19 | — | 0.30 |
| c | 0.09 | — | 0.20 |
| D | 4.90 | 5.00 | 5.10 |
| E1 | 4.30 | 4.40 | 4.50 |
| E | 6.40 BSC | | |
| [e] | 0.65 BSC | | |
| L1 | 1.00 REF | | |
| L | 0.45 | 0.60 | 0.75 |
| S | 0.20 | — | — |
| θ | 0° | — | 8° |

Notes:

1. Refer JEDEC MO-153F/AB
2. Controlling dimensions in millimeters
3. Package outline exclusive of mold flash and metal burr



DATE: 05/03/12

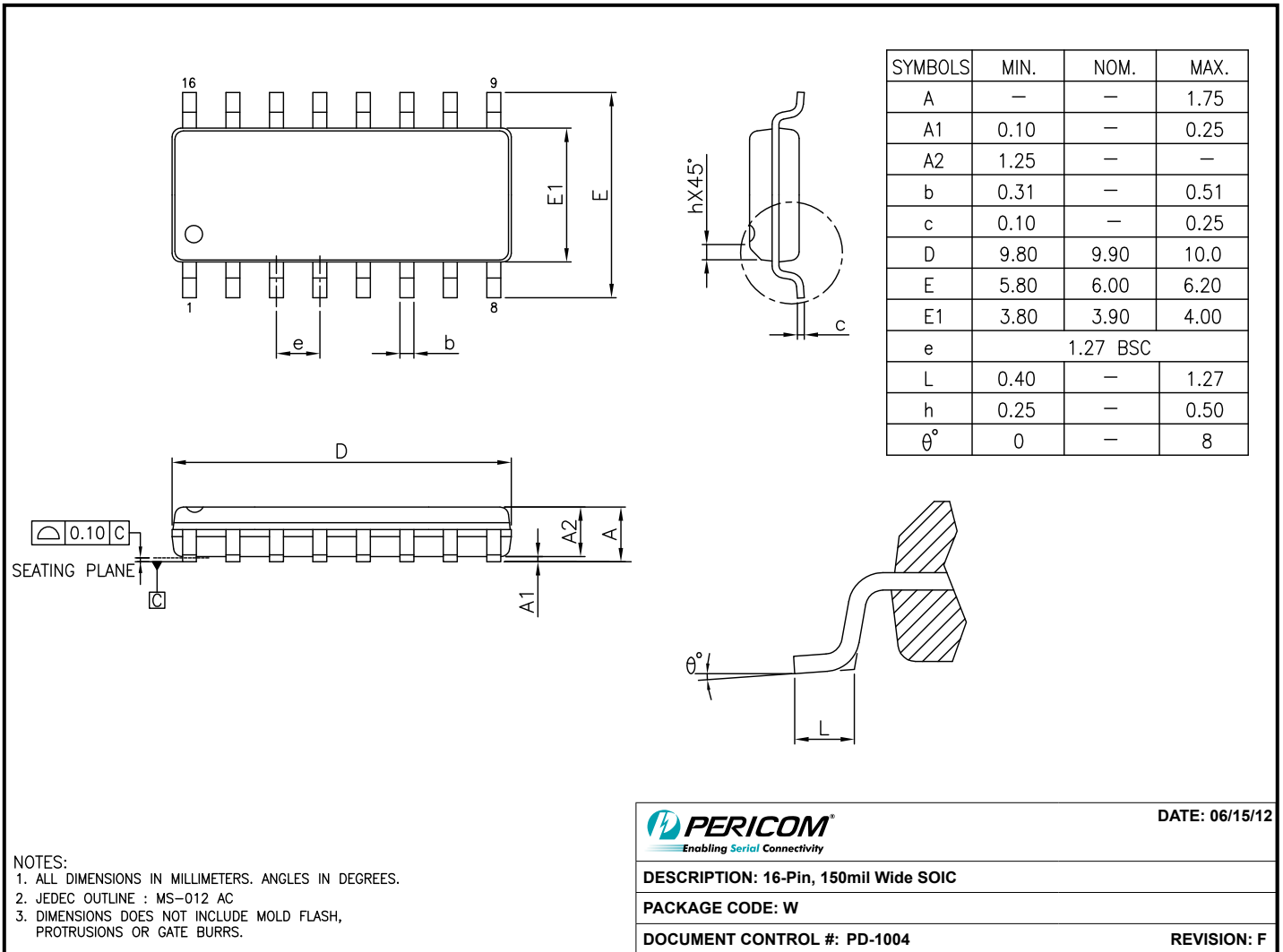
| |
|---|
| DESCRIPTION: 16-Pin, 173mil Wide TSSOP |
| PACKAGE CODE: L |
| DOCUMENT CONTROL #: PD-1310 |
| REVISION: F |

12-0372

Note:


- For latest package info, please check: <http://www.pericom.com/products/packaging/mechanicals.php>

Packaging Mechanical: 16-Pin SOIC (W)



| SYMBOLS | MIN. | NOM. | MAX. |
|----------------|----------|------|------|
| A | — | — | 1.75 |
| A1 | 0.10 | — | 0.25 |
| A2 | 1.25 | — | — |
| b | 0.31 | — | 0.51 |
| c | 0.10 | — | 0.25 |
| D | 9.80 | 9.90 | 10.0 |
| E | 5.80 | 6.00 | 6.20 |
| E1 | 3.80 | 3.90 | 4.00 |
| e | 1.27 BSC | | |
| L | 0.40 | — | 1.27 |
| h | 0.25 | — | 0.50 |
| θ° | 0 | — | 8 |

NOTES:
 1. ALL DIMENSIONS IN MILLIMETERS. ANGLES IN DEGREES.
 2. JEDEC OUTLINE : MS-012 AC
 3. DIMENSIONS DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

| | | |
|---|--|--------------------|
|  PERICOM Enabling Serial Connectivity | | DATE: 06/15/12 |
| DESCRIPTION: 16-Pin, 150mil Wide SOIC | | |
| PACKAGE CODE: W | | |
| DOCUMENT CONTROL #: PD-1004 | | REVISION: F |

2012-0398

Note:

• For latest package info, please check: <http://www.pericom.com/products/packaging/mechanicals.php>

Ordering Information(1,2,3)

| Ordering Code | Package Code | Package Type |
|---------------|--------------|--|
| PI6C22409LE | L | Pb-free & Green, 16-pin TSSOP |
| PI6C22409LIE | L | Pb-free & Green, 16-pin TSSOP, Industrial temp range |
| PI6C22409WE | W | Pb-free & Green, 16-pin SOIC |
| PI6C22409WIE | W | Pb-free & Green, 16-pin SOIC, Industrial temp range |

Notes:

1. Thermal characteristics can be found on the company web site at www.pericom.com/packaging/
2. E = Pb-free and Green
3. Adding an X suffix = Tape/Reel